CLAIMS

1. A method of peeling an electronic member (c) from a laminate composed of the electronic member (c) adhered to a supporting substrate (a) via an adhesive film (b), said adhesive film (b) having a self-peeling adhesive layer on a surface thereof located on the side of said supporting substrate (a) and an exposed region in at least one part of a surface thereof which is located on the side of said electronic member (c), the method comprising:

a step of reducing adhesive strength between said supporting substrate (a) and said self-peeling adhesive layer by applying energy on said exposed region;

a step of removing said supporting substrate (a) from the laminate by further applying energy on said region and thus further reducing the adhesive strength reduced in said prior step between said supporting substrate (a) and said self-peeling adhesive layer from a starting point of the interface between said supporting substrate (a) and said self-peeling adhesive layer; and

a step of peeling said electronic member (c) from the laminate by removing said adhesive film (b) from said electronic member (c).

2. A method of peeling an electronic member according to claim 1, wherein said energy is any one selected from heat, light, vibration, stress and ultrasonic waves.

3. A method of peeling an electronic member according to claim 1 or 2, wherein said exposed region in which said adhesive film (b) is exposed exists along the entire outer edge of said electronic member (c).

4. A method of peeling an electronic member according to any one of claims 1 to 3, wherein said electronic member (c) is a silicon wafer, a ceramic capacitor or a semiconductor package.

5. A laminate comprising:

a supporting substrate (a);

an adhesive film (b); and

an electronic member (c) adhered to said supporting substrate (a) via said adhesive film (b),

wherein said adhesive film (b) has a self-peeling adhesive layer on a surface thereof which is located on the side of said supporting substrate (a) and an exposed region in at least one part of a surface thereof which is located on the side of said electronic member (c).

CLAIMS

1. A method of peeling an electronic member (c) from a laminate composed of the electronic member (c) adhered to a supporting substrate (a) via an adhesive film (b), said adhesive film (b) having a self-peeling adhesive layer on a surface thereof located on a side that is facing said supporting substrate (a) and an exposed region in at least one part of a surface thereof which is located on a side that is facing said electronic member (c), the method comprising:

a step of reducing adhesive strength between said supporting substrate (a) and said self-peeling adhesive layer by applying energy on said exposed region;

a step of removing said supporting substrate (a) from the laminate by further applying energy on said region and thus further reducing the adhesive strength reduced in said prior step between said supporting substrate (a) and said self-peeling adhesive layer from a starting point of the interface between said supporting substrate (a) and said self-peeling adhesive layer; and

a step of peeling said electronic member (c) from the laminate by removing said adhesive film (b) from said electronic member (c).

2. A method of peeling an electronic member according to claim 1, wherein said energy is any one selected from heat, light, vibration, stress and ultrasonic waves.

3. A method of peeling an electronic member according to claim 1 or 2, wherein said exposed region in which said adhesive film (b) is exposed exists along the entire outer edge of said electronic member (c).

4. A method of peeling an electronic member according to any one of claims 1 to 3, wherein said electronic member (c) is a silicon wafer, a ceramic capacitor or a semiconductor package.